

Description

The 9DBL0442 / 9DBL0452 devices are 3.3V members of IDT's Full-Featured PCIe family. The 9DBL0442 / 9DBL0452 supports PCIe Gen1-4 Common Clocked (CC) and PCIe Separate Reference Independent Spread (SRIS) systems. It offers a choice of integrated output terminations providing direct connection to 85Ω or 100Ω transmission lines. The 9DBL04P2 can be factory programmed with a user-defined power up default SMBus configuration.

Recommended Application

PCIe Gen1-4 clock distribution for Riser Cards, Storage, Networking, JBOD, Communications, Access Points

Output Features

- 4 – 1-200 MHz Low-Power (LP) HCSL DIF pairs
 - 9DBL0442 default Z_{OUT} = 100Ω
 - 9DBL0452 default Z_{OUT} = 85Ω
 - 9DBL04P2 factory programmable defaults
- Easy AC-coupling to other logic families, see IDT application note [AN-891](#)

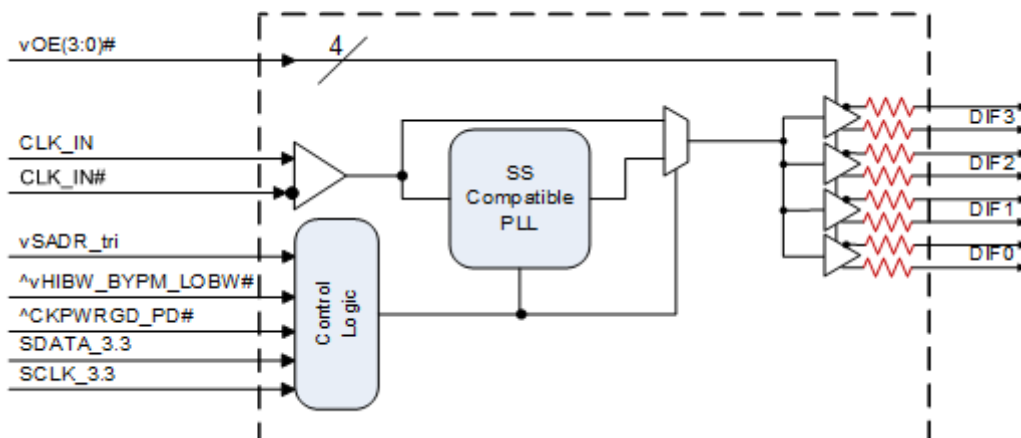
Key Specifications

- PCIe Gen1-2-3-4 CC compliant in ZDB mode
- PCIe Gen2 SRIS compliant in ZDB mode
- Supports PCIe Gen2-3 SRIS in fan-out mode
- DIF cycle-to-cycle jitter < 50ps
- DIF output-to-output skew < 50ps
- Bypass mode *additive* phase jitter is 0 ps typical rms for PCIe
- Bypass mode additive phase jitter 160fs rms typ. @ 156.25M (1.5M to 10M)

Features/Benefits

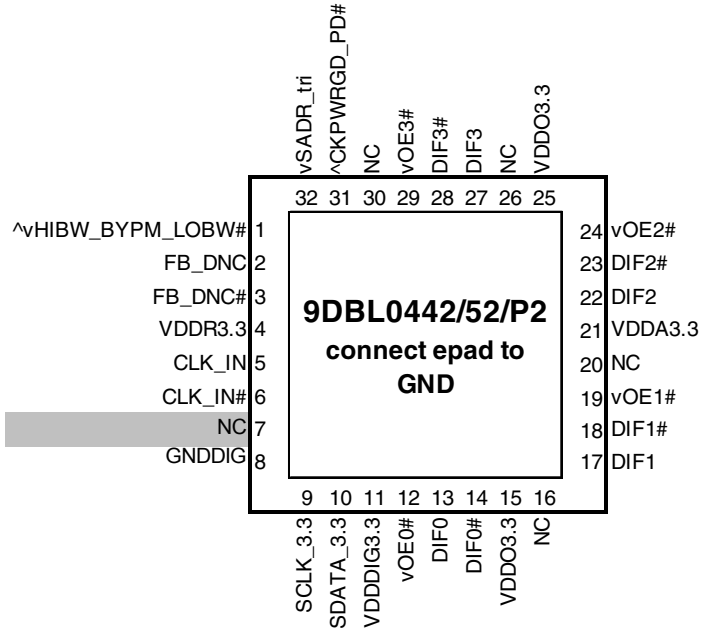
- Direct connection to 100Ω (xx42) or 85Ω (xx52) transmission lines; saves 16 resistors compared to standard PCIe devices
- 132mW typical power consumption in PLL mode; eliminates thermal concerns
- SMBus-selectable features allows optimization to customer requirements:
 - control input polarity
 - control input pull up/downs
 - slew rate for each output
 - differential output amplitude
 - output impedance for each output
 - 50, 100, 125MHz operating frequency
- Customer defined SMBus power up default can be programmed into P2 device; allows exact optimization to customer requirements
- OE# pins; support DIF power management
- HCSL-compatible differential input; can be driven by common clock sources
- Spread Spectrum tolerant; allows reduction of EMI
- Pin/SMBus selectable PLL bandwidth and PLL Bypass; minimize phase jitter for each application
- Outputs blocked until PLL is locked; clean system start-up
- Device contains default configuration; SMBus interface not required for device operation
- Three selectable SMBus addresses; multiple devices can easily share an SMBus segment
- 5 × 5 mm 32-VFQFPN package; minimal board space

Block Diagram



Note: Resistors default to internal on xx42/xx52 devices. P2 devices have programmable default impedances on an output-by-output basis.

Pin Configuration



32-pin VFQFPN, 5x5 mm, 0.5mm pitch

^ prefix indicates internal 120KOhm pull up resistor

^v prefix indicates internal 120KOhm pull up AND pull down resistor (biased to VDD/2)

v prefix indicates internal 120KOhm pull down resistor

SMBus Address Selection Table

| | SADR | Address | + Read/Write bit |
|---|------|---------|------------------|
| State of SADR on first application of CKPWRGD_PD# | 0 | 1101011 | x |
| | M | 1101100 | x |
| | 1 | 1101101 | x |

Power Management Table

| CKPWRGD_PD# | CLK_IN | SMBus OE bit | OEx# Pin | DIFx/DIFx# | | PLL |
|-------------|---------|--------------|----------|-----------------------|-----------------------|-----------------|
| | | | | True O/P | Comp. O/P | |
| 0 | X | X | X | Low ¹ | Low ¹ | Off |
| 1 | Running | 1 | 0 | Running | Running | On ³ |
| 1 | Running | 1 | 1 | Disabled ¹ | Disabled ¹ | On ³ |
| 1 | Running | 0 | X | Disabled ¹ | Disabled ¹ | On ³ |

1. The output state is set by B11[1:0] (Low/Low default)

2. Input polarities defined as default values for xx42/xx52 devices.

3. If Bypass mode is selected, the PLL will be off, and outputs will be running.

Power Connections

| Pin Number | | Description |
|------------|-----|-----------------------|
| VDD | GND | |
| 4 | 33 | Input receiver analog |
| 11 | 8 | Digital Power |
| 15,25 | 33 | DIF outputs |
| 21 | 33 | PLL Analog |

PLL Operating Mode

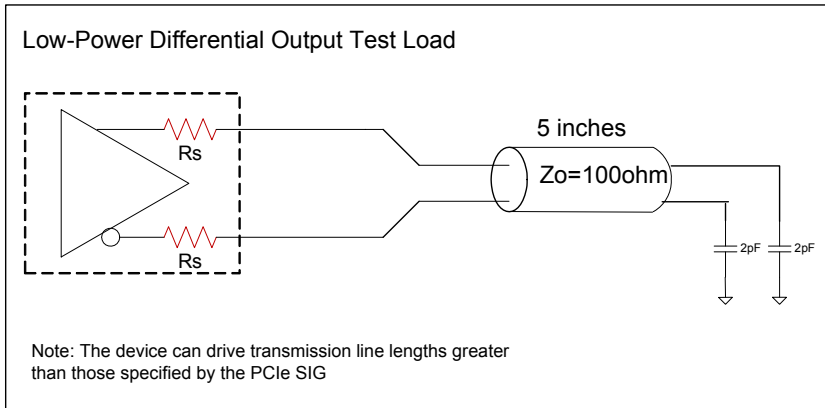
| HiBW_ByPM_LoBW# | MODE | Byte1 [7:6] Readback | Byte1 [4:3] Control |
|-----------------|-----------|----------------------|---------------------|
| 0 | PLL Lo BW | 00 | 00 |
| M | Bypass | 01 | 01 |
| 1 | PLL Hi BW | 11 | 11 |

Pin Descriptions

| Pin# | Pin Name | Type | Pin Description |
|------|-----------------|------------|---|
| 1 | ^vHIBW_BYPM_LOB | LATCHED IN | Tri-level input to select High BW, Bypass or Low BW mode. This pin is biased to VDD/2 (Bypass mode) with internal pull up/pull down resistors. See PLL Operating Mode Table for Details. |
| 2 | FB_DNC | DNC | True clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin. |
| 3 | FB_DNC# | DNC | Complement clock of differential feedback. The feedback output and feedback input are connected internally on this pin. Do not connect anything to this pin. |
| 4 | VDDR3.3 | PWR | 3.3V power for differential input clock (receiver). This VDD should be treated as an Analog power rail and filtered appropriately. |
| 5 | CLK_IN | IN | True Input for differential reference clock. |
| 6 | CLK_IN# | IN | Complementary Input for differential reference clock. |
| 7 | NC | N/A | No Connection. |
| 8 | GNDDIG | GND | Ground pin for digital circuitry |
| 9 | SCLK_3.3 | IN | Clock pin of SMBus circuitry, 3.3V tolerant. |
| 10 | SDATA_3.3 | I/O | Data pin for SMBus circuitry, 3.3V tolerant. |
| 11 | VDDDIG3.3 | PWR | 3.3V digital power (dirty power) |
| 12 | vOE0# | IN | Active low input for enabling output 0. This pin has an internal 120kohm pull-down. 1 =disable outputs, 0 = enable outputs |
| 13 | DIF0 | OUT | Differential true clock output |
| 14 | DIF0# | OUT | Differential Complementary clock output |
| 15 | VDDO3.3 | PWR | Power supply for outputs,nominal 3.3V. |
| 16 | NC | N/A | No Connection. |
| 17 | DIF1 | OUT | Differential true clock output |
| 18 | DIF1# | OUT | Differential Complementary clock output |
| 19 | vOE1# | IN | Active low input for enabling output 1. This pin has an internal 120kohm pull-down. 1 =disable outputs, 0 = enable outputs |
| 20 | NC | N/A | No Connection. |
| 21 | VDDA3.3 | PWR | 3.3V power for the PLL core. |
| 22 | DIF2 | OUT | Differential true clock output |
| 23 | DIF2# | OUT | Differential Complementary clock output |
| 24 | vOE2# | IN | Active low input for enabling output 2. This pin has an internal 120kohm pull-down. 1 =disable outputs, 0 = enable outputs |
| 25 | VDDO3.3 | PWR | Power supply for outputs,nominal 3.3V. |
| 26 | NC | N/A | No Connection. |
| 27 | DIF3 | OUT | Differential true clock output |
| 28 | DIF3# | OUT | Differential Complementary clock output |
| 29 | vOE3# | IN | Active low input for enabling output 3. This pin has an internal 120kohm pull-down. 1 =disable outputs, 0 = enable outputs |
| 30 | NC | N/A | No Connection. |
| 31 | ^CKPWRGD_PD# | IN | Input notifies device to sample latched inputs and start up on first high assertion. Low enters Power Down Mode, subsequent high assertions exit Power Down Mode. This pin has internal 120kohm pull-up resistor. |
| 32 | vSADR_tri | LATCHED IN | Tri-level latch to select SMBus Address. It has an internal 120kohm pull down resistor. See SMBus Address Selection Table. |
| 33 | epad | GND | connect epad to ground. |

NOTE: DNC indicates Do Not Connect anything to this pin.

Test Loads



Terminations

| Device | Zo (Ω) | Rs (Ω) |
|----------|-----------------|-----------------|
| 9DBL0442 | 100 | None needed |
| 9DBL0452 | 100 | 7.5 |
| 9DBL04P2 | 100 | Prog. |
| 9DBL0442 | 85 | N/A |
| 9DBL0452 | 85 | None needed |
| 9DBL04P2 | 85 | Prog. |

Alternate Terminations

The 9DBL family can easily drive LVPECL, LVDS, and CML logic. See [“AN-891 Driving LVPECL, LVDS, and CML Logic with IDT's "Universal" Low-Power HCSL Outputs”](#) for details.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9DBL0442 / 9DBL0452. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|---------------------------|--------------------|---------------------------|------|-----|----------------------|-------|-------|
| Supply Voltage | VDDx | | | | 4.6 | V | 1,2 |
| Input Voltage | V _{IN} | | -0.5 | | V _{DD} +0.5 | V | 1,3 |
| Input High Voltage, SMBus | V _{IHSMB} | SMBus clock and data pins | | | 3.9 | V | 1 |
| Storage Temperature | T _s | | -65 | | 150 | °C | 1 |
| Junction Temperature | T _j | | | | 125 | °C | 1 |
| Input ESD protection | ESD prot | Human Body Model | 2500 | | | V | 1 |

¹Guaranteed by design and characterization, not 100% tested in production.

²Operation under these conditions is neither implied nor guaranteed.

³Not to exceed 4.6V.

Electrical Characteristics–Clock Input Parameters

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|----------------------------------|--------------------|---|-----|-----|-----|-------|-------|
| Input Crossover Voltage - DIF_IN | V _{CROSS} | Cross Over Voltage | 150 | | 900 | mV | 1 |
| Input Swing - DIF_IN | V _{SWING} | Differential value | 300 | | | mV | 1 |
| Input Slew Rate - DIF_IN | dv/dt | Measured differentially | 0.4 | | 8 | V/ns | 1,2 |
| Input Leakage Current | I _{IN} | V _{IN} = V _{DD} , V _{IN} = GND | -5 | | 5 | uA | |
| Input Duty Cycle | d _{tin} | Measurement from differential wavefrom | 45 | | 55 | % | 1 |
| Input Jitter - Cycle to Cycle | J _{DIFin} | Differential Measurement | 0 | | 125 | ps | 1 |

¹Guaranteed by design and characterization, not 100% tested in production.

²Slew rate measured through +/-75mV window centered around differential zero

Electrical Characteristics–SMBus Parameters

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|---------------------------|---------------------|--------------------------------------|-----|-----|------|-------|-------|
| SMBus Input Low Voltage | V _{ILSMB} | V _{DD} SMB = 3.3V | | | 0.8 | V | |
| SMBus Input High Voltage | V _{IHSMB} | V _{DD} SMB = 3.3V | 2.1 | | 3.6 | V | |
| SMBus Output Low Voltage | V _{OLSMB} | @ I _{PULLUP} | | | 0.4 | V | |
| SMBus Sink Current | I _{PULLUP} | @ V _{OL} | 4 | | | mA | |
| Nominal Bus Voltage | V _{DD} SMB | | 2.7 | | 3.6 | V | |
| SCLK/SDATA Rise Time | t _{RSMB} | (Max VIL - 0.15) to (Min VIH + 0.15) | | | 1000 | ns | 1 |
| SCLK/SDATA Fall Time | t _{FSMB} | (Min VIH + 0.15) to (Max VIL - 0.15) | | | 300 | ns | 1 |
| SMBus Operating Frequency | f _{SMB} | SMBus operating frequency | | | 500 | kHz | 2,3 |

¹Guaranteed by design and characterization, not 100% tested in production.

²The device must be powered up for the SMBus to function.

³The differential input clock must be running for the SMBus to be active

Electrical Characteristics–Input/Supply/Common Parameters–Normal Operating Conditions

$T_A = T_{AMB}$, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|--|-----------------|---|----------------|---------------|-----------------|--------|-------|
| Supply Voltage | VDDx | Supply voltage for core and analog | 3.135 | 3.3 | 3.465 | V | |
| Ambient Operating Temperature | T_{AMB} | Industrial range | -40 | 25 | 85 | °C | |
| Input High Voltage | V_{IH} | Single-ended inputs, except SMBus | $0.75 V_{DDx}$ | | $V_{DDx} + 0.3$ | V | |
| Input Low Voltage | V_{IL} | | -0.3 | | $0.25 V_{DDx}$ | V | |
| Input High Voltage | V_{IHtri} | Single-ended tri-level inputs ('_tri' suffix) | $0.75 V_{DDx}$ | | $V_{DD} + 0.3$ | V | |
| Input Mid Voltage | V_{IMtri} | | $0.4 V_{DDx}$ | $0.5 V_{DDx}$ | $0.6 V_{DDx}$ | V | |
| Input Low Voltage | V_{ILtri} | | -0.3 | | $0.25 V_{DDx}$ | V | |
| Input Current | I_{IN} | Single-ended inputs, $V_{IN} = GND$, $V_{IN} = VDD$ | -5 | | 5 | uA | |
| | I_{INP} | Single-ended inputs $V_{IN} = 0 V$; Inputs with internal pull-up resistors $V_{IN} = VDD$; Inputs with internal pull-down resistors | -50 | | 50 | uA | |
| Input Frequency | F_{IN} | Bypass mode | 1 | | 200 | MHz | 2 |
| | | 100MHz PLL mode | 60 | 100.00 | 140 | MHz | 2 |
| | | 50MHz PLL mode | 30 | 50.00 | 65 | MHz | 2 |
| | | 125MHz PLL mode | 75 | 125.00 | 175 | MHz | 2 |
| Pin Inductance | L_{pin} | | | 7 | nH | 1 | |
| Capacitance | C_{IN} | Logic Inputs, except DIF_IN | 1.5 | | 5 | pF | 1 |
| | C_{INDIF_IN} | DIF_IN differential clock inputs | 1.5 | | 2.7 | pF | 1 |
| | C_{OUT} | Output pin capacitance | | | 6 | pF | 1 |
| Clk Stabilization | T_{STAB} | From V_{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock | | | 1 | ms | 1,2 |
| Input SS Modulation Frequency PCIe | $f_{MODINPCIe}$ | Allowable Frequency for PCIe Applications (Triangular Modulation) | 30 | | 33 | kHz | |
| Input SS Modulation Frequency non-PCIe | f_{MODIN} | Allowable Frequency for non-PCIe Applications (Triangular Modulation) | 0 | | 66 | kHz | |
| OE# Latency | $t_{LATOE\#}$ | DIF start after OE# assertion DIF stop after OE# deassertion | 1 | | 3 | clocks | 1,3 |
| Tdrive_PD# | t_{DRVPD} | DIF output enable after PD# de-assertion | | | 300 | us | 1,3 |
| Tfall | t_F | Fall time of single-ended control inputs | | | 5 | ns | 2 |
| Trise | t_R | Rise time of single-ended control inputs | | | 5 | ns | 2 |

¹Guaranteed by design and characterization, not 100% tested in production.

²Control input must be monotonic from 20% to 80% of input swing.

³Time from deassertion until outputs are >200 mV

Electrical Characteristics–DIF Low-Power HCSL Outputs

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|------------------------|------------------------------|---|------|-----|------|-------|-------|
| Slew rate | dV/dt | Scope averaging on, fast setting | 2 | 2.8 | 4 | V/ns | 1,2,3 |
| | dV/dt | Scope averaging on, slow setting | 1.2 | 1.9 | 3.1 | V/ns | 1,2,3 |
| Slew rate matching | Δ dV/dt | Slew rate matching | | 7 | 20 | % | 1,2,4 |
| Voltage High | V _{HIGH} | Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging on) | 660 | 768 | 850 | mV | 7 |
| Voltage Low | V _{LOW} | | -150 | -11 | 150 | | 7 |
| Max Voltage | V _{max} | Measurement on single ended signal using absolute value. (Scope averaging off) | | 811 | 1150 | mV | 7 |
| Min Voltage | V _{min} | | -300 | -49 | | | 7 |
| Crossing Voltage (abs) | V _{cross_abs} | Scope averaging off | 250 | 357 | 550 | mV | 1,5 |
| Crossing Voltage (var) | Δ -V _{cross} | Scope averaging off | | 14 | 140 | mV | 1,6 |

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Slew rate is measured through the V_{swing} voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ V_{cross} is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all V_{cross} measurements in any particular system. Note that this is a subset of V_{cross_min/max} (V_{cross} absolute) allowed. The intent is to limit V_{cross} induced modulation by setting Δ -V_{cross} to be smaller than V_{cross} absolute.

⁷ At default SMBus settings.

Electrical Characteristics–Current Consumption

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|--------------------------|----------------------|--|-----|------|-----|-------|-------|
| Operating Supply Current | I _{DDA} | VDDA, PLL Mode @100MHz | | 7 | 10 | mA | |
| | I _{DDDIG} | VDDDIG, PLL Mode @100MHz | | 3.4 | 5 | mA | |
| | I _{DDO+R} | VDDO+VDDR, PLL Mode, All outputs @100MHz | | 30.0 | 37 | mA | |
| Powerdown Current | I _{DDRPD} | VDDA, CKPWRGD_PD# = 0 | | 0.6 | 1.0 | mA | 1 |
| | I _{DDDIGPD} | VDDDIG, CKPWRGD_PD# = 0 | | 3.1 | 4.3 | mA | 1 |
| | I _{DDAOPD} | VDDO+VDDR, CKPWRGD_PD# = 0 | | 0.9 | 1.3 | mA | 1 |

¹ Input clock stopped.

Electrical Characteristics–Output Duty Cycle, Jitter, Skew and PLL Characteristics

TA = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS | NOTES |
|------------------------|-----------------------|--------------------------------------|------|------|------|-------|-------|
| PLL Bandwidth | BW | -3dB point in High BW Mode (100MHz) | 2 | 3.3 | 4 | MHz | 1,5 |
| | | -3dB point in Low BW Mode (100MHz) | 1 | 1.5 | 2 | MHz | 1,5 |
| PLL Jitter Peaking | t _{JPEAK} | Peak Pass band Gain (100MHz) | | 0.8 | 2 | dB | 1 |
| Duty Cycle | t _{DC} | Measured differentially, PLL Mode | 45 | 50 | 55 | % | 1 |
| Duty Cycle Distortion | t _{DCD} | Measured differentially, Bypass Mode | -1 | 0.0 | 1 | % | 1,3 |
| Skew, Input to Output | t _{pdBYP} | Bypass Mode, V _T = 50% | 2500 | 3406 | 4500 | ps | 1 |
| | t _{pdPLL} | PLL Mode V _T = 50% | -100 | 8 | 100 | ps | 1,4 |
| Skew, Output to Output | t _{sk3} | V _T = 50% | | 21 | 55 | ps | 1,4 |
| | | PLL mode | | 15 | 50 | ps | 1,2 |
| Jitter, Cycle to cycle | t _{jycy-cyc} | | | 0.1 | 1 | ps | 1,2 |
| | | Additive Jitter in Bypass Mode | | | | | |

¹ Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

⁴ All outputs at default slew rate

⁵ The MIN/TYP/MAX values of each BW setting track each other, i.e., Low BW MAX will never occur with Hi BW MIN.

Electrical Characteristics–Filtered Phase Jitter Parameters - PCIe Common Clocked (CC) Architectures

T_{AMB} = over the specified operating range. Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | INDUSTRY LIMIT | UNITS | Notes |
|------------------------------------|---------------------------|---|-----|-----|------|----------------|----------|---------|
| Phase Jitter, PLL Mode | t _{jphPCIeG1-CC} | PCIe Gen 1 | | 23 | 32 | 86 | ps (p-p) | 1,2,3,5 |
| | t _{jphPCIeG2-CC} | PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz) | | 0.6 | 0.8 | 3 | ps (rms) | 1,2,5 |
| | | PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz) (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz) | | 1.7 | 2.1 | 3.1 | ps (rms) | 1,2,5 |
| | t _{jphPCIeG3-CC} | PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.4 | 0.48 | 1 | ps (rms) | 1,2,5 |
| | t _{jphPCIeG4-CC} | PCIe Gen 4 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.4 | 0.48 | 0.5 | ps (rms) | 1,2,5 |
| Additive Phase Jitter, Bypass mode | t _{jphPCIeG1-CC} | PCIe Gen 1 | | 0.0 | 0.01 | n/a | ps (p-p) | 1,2,5 |
| | t _{jphPCIeG2-CC} | PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,5 |
| | | PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz) (PLL BW of 5-16MHz or 8-5MHz, CDR = 5MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,5 |
| | t _{jphPCIeG3-CC} | PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,5 |
| | t _{jphPCIeG4-CC} | PCIe Gen 4 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,5 |

¹ Applies to all outputs.

² Based on PCIe Base Specification Rev4.0 version 0.7draft. See <http://www.pcisig.com> for latest specifications.

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ For RMS values additive jitter is calculated by solving the following equation for b [$a^2 + b^2 = c^2$] where a is rms input jitter and c is rms total jitter.

⁵ Driven by 9FGL0841 or equivalent

Electrical Characteristics—Filtered Phase Jitter Parameters - PCIe Separate Reference Independent Spread (SRIS) Architectures⁵

T_{AMB} = over the specified operating range. Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | INDUSTRY LIMIT | UNITS | Notes |
|------------------------------------|-----------------------------|---|-----|-----|------|----------------|----------|---------|
| Phase Jitter, PLL Mode | t _{jphPCIeG2-SRIS} | PCIe Gen 2 (PLL BW of 16MHz , CDR = 5MHz) | | 1.2 | 1.5 | 2 | ps (rms) | 1,2 |
| | t _{jphPCIeG3-SRIS} | PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | n/a | | 0.5 | ps (rms) | 1,2,6 |
| Additive Phase Jitter, Bypass mode | t _{jphPCIeG2-SRIS} | PCIe Gen 2 (PLL BW of 16MHz , CDR = 5MHz) | | 0.0 | 0.01 | n/a | ps (rms) | 1,2,4 |
| | t _{jphPCIeG3-SRIS} | PCIe Gen 3 (PLL BW of 2-4MHz or 2-5MHz, CDR = 10MHz) | | 0.0 | 0.01 | | ps (rms) | 1,2,4,6 |

¹ Applies to all outputs.

² Based on PCIe Base Specification Rev3.1a. These filters are different than Common Clock filters. See <http://www.pcisig.com> for latest specifications.

³ Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

⁴ For RMS values, additive jitter is calculated by solving the following equation for b [$a^2+b^2=c^2$] where a is rms input jitter and c is rms total jitter.

⁵ As of PCIe Base Specification Rev4.0 draft 0.7, SRIS is not currently defined for Gen1 or Gen4.

⁶ This device does not support PCIe Gen3 SRIS in PLL mode. It supports PCIe Gen3 SRIS in bypass mode.

Electrical Characteristics—Unfiltered Phase Jitter Parameters

T_A = T_{AMB}, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | INDUSTRY LIMIT | UNITS | Notes |
|------------------------------------|----------------------------|--|-----|-----|-----|----------------|----------|-------|
| Additive Phase Jitter, Fanout Mode | t _{jph156M} | 156.25MHz, 1.5MHz to 10MHz, -20dB/decade rollover < 1.5MHz, -40db/decade rolloff > 10MHz | | 159 | | N/A | fs (rms) | 1,2,3 |
| | t _{jph156M12k-20} | 156.25MHz, 12kHz to 20MHz, -20dB/decade rollover <12kHz, -40db/decade rolloff > 20MHz | | 363 | | N/A | fs (rms) | 1,2,3 |

¹Guaranteed by design and characterization, not 100% tested in production.

² Driven by Rohde&Schartz SMA100

³ For RMS figures, additive jitter is calculated by solving the following equation: Additive jitter = SQRT[(total jitter)² - (input jitter)²]

General SMBus Serial Interface Information

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) sends the byte count = X
- IDT clock will **acknowledge**
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

| Index Block Write Operation | | | |
|-----------------------------|-----------|-----------|----------------------|
| Controller (Host) | | | IDT (Slave/Receiver) |
| T | starT bit | | |
| Slave Address | | | |
| WR | WRite | | |
| | | | ACK |
| Beginning Byte = N | | | |
| | | | ACK |
| Data Byte Count = X | | | |
| | | | ACK |
| Beginning Byte N | | X Byte | |
| O | | | ACK |
| O | | | O |
| O | | | O |
| | | | O |
| Byte N + X - 1 | | | |
| | | | ACK |
| P | stoP bit | | |

Note: SMBus Address is Latched on SADR pin. Unless otherwise indicated, default values are for the xx42 and xx52. P2 devices are fully factory programmable.

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will **acknowledge**
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends **Byte 0 through Byte X (if X_(H) was written to Byte 8)**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

| Index Block Read Operation | | | |
|----------------------------|-----------------|-----------|----------------------|
| Controller (Host) | | | IDT (Slave/Receiver) |
| T | starT bit | | |
| Slave Address | | | |
| WR | WRite | | |
| | | | ACK |
| Beginning Byte = N | | | |
| | | | ACK |
| RT | Repeat starT | | |
| Slave Address | | | |
| RD | ReaD | | |
| | | | ACK |
| | | | Data Byte Count=X |
| ACK | | X Byte | |
| ACK | | | Beginning Byte N |
| | | | O |
| | | | O |
| | | | O |
| | | | Byte N + X - 1 |
| N | Not acknowledge | | |
| P | stoP bit | | |

SMBus Table: Output Enable Register ¹

| Byte 0 | Name | Control Function | Type | 0 | 1 | Default |
|--------|----------|------------------|------|--------------|-------------|---------|
| Bit 7 | Reserved | | | See B11[1:0] | | 0 |
| Bit 6 | DIF OE3 | Output Enable | RW | | Pin Control | 1 |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | DIF OE2 | Output Enable | RW | | Pin Control | 1 |
| Bit 3 | DIF OE1 | Output Enable | RW | | Pin Control | 1 |
| Bit 2 | Reserved | | | | | 0 |
| Bit 1 | DIF OE0 | Output Enable | RW | | Pin Control | 1 |
| Bit 0 | Reserved | | | | | 0 |

1. A low on these bits will override the OE# pin and force the differential output to the state indicated by B11[1:0] (Low/Low default)

SMBus Table: PLL Operating Mode and Output Amplitude Control Register

| Byte 1 | Name | Control Function | Type | 0 | 1 | Default |
|--------|-----------------|-------------------------------|-----------------|--------------------------------|--------------------------------|---------|
| Bit 7 | PLLMODERB1 | PLL Mode Readback Bit 1 | R | See PLL Operating Mode Table | | Latch |
| Bit 6 | PLLMODERB0 | PLL Mode Readback Bit 0 | R | | | Latch |
| Bit 5 | PLLMODE_SWCNTRL | Enable SW control of PLL Mode | RW | Values in B1[7:6] set PLL Mode | Values in B1[4:3] set PLL Mode | 0 |
| Bit 4 | PLLMODE1 | PLL Mode Control Bit 1 | RW ¹ | See PLL Operating Mode Table | | 0 |
| Bit 3 | PLLMODE0 | PLL Mode Control Bit 0 | RW ¹ | | | 0 |
| Bit 2 | Reserved | | | | | 1 |
| Bit 1 | AMPLITUDE 1 | Controls Output Amplitude | RW | 00 = 0.6V | 01 = 0.68V | 1 |
| Bit 0 | AMPLITUDE 0 | | RW | 10 = 0.75V | 11 = 0.85V | 0 |

1. B1[5] must be set to a 1 for these bits to have any effect on the part.

SMBus Table: Slew Rate Control Register

| Byte 2 | Name | Control Function | Type | 0 | 1 | Default |
|--------|------------------|---------------------|------|--------------|--------------|---------|
| Bit 7 | Reserved | | | | | 1 |
| Bit 6 | SLEWRATESEL DIF3 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |
| Bit 5 | Reserved | | | | | 1 |
| Bit 4 | SLEWRATESEL DIF2 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |
| Bit 3 | SLEWRATESEL DIF1 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |
| Bit 2 | Reserved | | | | | 1 |
| Bit 1 | SLEWRATESEL DIF0 | Slew rate selection | RW | Slow Setting | Fast Setting | 1 |
| Bit 0 | Reserved | | | | | 1 |

Note: See "Low-Power HCSL Outputs" table for slew rates.

SMBus Table: Slew Rate Control Register

| Byte 3 | Name | Control Function | Type | 0 | 1 | Default |
|--------|----------------|----------------------------------|-----------------|---|-----------------------------|---------|
| Bit 7 | Reserved | | | | | 1 |
| Bit 6 | Reserved | | | | | 1 |
| Bit 5 | FREQ_SEL_EN | Enable SW selection of frequency | RW | SW frequency change disabled | SW frequency change enabled | 0 |
| Bit 4 | FSEL1 | Freq. Select Bit 1 | RW ¹ | 00 = 100M, 10 = 125M 01 = 50M, 11 = Reserved | | 0 |
| Bit 3 | FSEL0 | Freq. Select Bit 0 | RW ¹ | | | 0 |
| Bit 2 | Reserved | | | | | 1 |
| Bit 1 | Reserved | | | | | 1 |
| Bit 0 | SLEWRATESEL FB | Adjust Slew Rate of FB | RW | Slow Setting | Fast Setting | 1 |

1. B3[5] must be set to a 1 for these bits to have any effect on the part.

Byte 4 is Reserved

SMBus Table: Revision and Vendor ID Register

| Byte 5 | Name | Control Function | Type | 0 | 1 | Default |
|--------|------|------------------|------|--------------|---|---------|
| Bit 7 | RID3 | Revision ID | R | B rev = 0000 | | 0 |
| Bit 6 | RID2 | | R | | | 0 |
| Bit 5 | RID1 | | R | | | 0 |
| Bit 4 | RID0 | | R | | | 1 |
| Bit 3 | VID3 | VENDOR ID | R | 0001 = IDT | | 0 |
| Bit 2 | VID2 | | R | | | 0 |
| Bit 1 | VID1 | | R | | | 0 |
| Bit 0 | VID0 | | R | | | 1 |

SMBus Table: Device Type/Device ID

| Byte 6 | Name | Control Function | Type | 0 | 1 | Default |
|--------|--------------|------------------|------|--|---|---------|
| Bit 7 | Device Type1 | Device Type | RW | 00 = FGx, 01 = DBx ZDB/FOB, 10 = DMx, 11= DBx FOB | | 0 |
| Bit 6 | Device Type0 | | RW | | | 1 |
| Bit 5 | Device ID5 | Device ID | RW | 000110binary or 04 hex | | 0 |
| Bit 4 | Device ID4 | | RW | | | 0 |
| Bit 3 | Device ID3 | | RW | | | 0 |
| Bit 2 | Device ID2 | | RW | | | 1 |
| Bit 1 | Device ID1 | | RW | | | 0 |
| Bit 0 | Device ID0 | | RW | | | 0 |

SMBus Table: Byte Count Register

| Byte 7 | Name | Control Function | Type | 0 | 1 | Default |
|--------|------|------------------------|------|---|---|---------|
| Bit 7 | | Reserved | | | | 0 |
| Bit 6 | | Reserved | | | | 0 |
| Bit 5 | | Reserved | | | | 0 |
| Bit 4 | BC4 | Byte Count Programming | RW | Writing to this register will configure how many bytes will be read back, default is = 8 bytes. | | 0 |
| Bit 3 | BC3 | | RW | | | 1 |
| Bit 2 | BC2 | | RW | | | 0 |
| Bit 1 | BC1 | | RW | | | 0 |
| Bit 0 | BC0 | | RW | | | 0 |

Bytes 8 and 9 are Reserved

SMBus Table: PD_Restore

| Byte 10 | Name | Control Function | Type | 0 | 1 | Default |
|---------|-------------------------|-------------------------------|------|--------------------|-------------------|---------|
| Bit 7 | | Reserved | | | | 1 |
| Bit 6 | Power-Down (PD) Restore | Restore Default Config. In PD | RW | Clear Config in PD | Keep Config in PD | 1 |
| Bit 5 | | Reserved | | | | 0 |
| Bit 4 | | Reserved | | | | 0 |
| Bit 3 | | Reserved | | | | 0 |
| Bit 2 | | Reserved | | | | 0 |
| Bit 1 | | Reserved | | | | 0 |
| Bit 0 | | Reserved | | | | 0 |

SMBus Table: Stop State and Impedance Control

| Byte 11 | Name | Control Function | Type | 0 | 1 | Default |
|---------|-----------|---|------|-----------------|------------------|----------|
| Bit 7 | FB_imp[1] | FB Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | see Note |
| Bit 6 | FB_imp[0] | | RW | 01=85Ω DIF Zout | 11 = Reserved | |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | Reserved | | | | | 0 |
| Bit 3 | Reserved | | | | | 0 |
| Bit 2 | Reserved | | | | | 0 |
| Bit 1 | STP[1] | True/Complement DIF Output Disable State | RW | 00 = Low/Low | 10 = High/Low | 0 |
| Bit 0 | STP[0] | | RW | 01 = HiZ/HiZ | 11 = Low/High | 0 |

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

SMBus Table: Impedance Control

| Byte 12 | Name | Control Function | Type | 0 | 1 | Default |
|---------|-------------|------------------|------|-----------------|------------------|----------|
| Bit 7 | DIF1_imp[1] | DIF3 Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | see Note |
| Bit 6 | DIF1_imp[0] | | RW | 01=85Ω DIF Zout | 11 = Reserved | |
| Bit 5 | Reserved | | | | | |
| Bit 4 | Reserved | | | | | |
| Bit 3 | DIF0_imp[1] | DIF1 Zout | RW | 00=33Ω DIF Zout | 10=100Ω DIF Zout | |
| Bit 2 | DIF1_imp[0] | | RW | 01=85Ω DIF Zout | 11 = Reserved | |
| Bit 1 | Reserved | | | | | |
| Bit 0 | Reserved | | | | | |

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

SMBus Table: Impedance Control

| Byte 13 | Name | Control Function | Type | 0 | 1 | Default |
|---------|-------------|------------------|------|-----------------------------|------------------------------|----------|
| Bit 7 | Reserved | | | | | see Note |
| Bit 6 | Reserved | | | | | |
| Bit 5 | DIF3_imp[1] | DIF6 Zout | RW | 00=33 _Ω DIF Zout | 10=100 _Ω DIF Zout | |
| Bit 4 | DIF3_imp[0] | DIF6 Zout | RW | 01=85 _Ω DIF Zout | 11 = Reserved | |
| Bit 3 | Reserved | | | | | |
| Bit 2 | Reserved | | | | | |
| Bit 1 | DIF2_imp[1] | DIF4 Zout | RW | 00=33 _Ω DIF Zout | 10=100 _Ω DIF Zout | |
| Bit 0 | DIF2_imp[0] | DIF4 Zout | RW | 01=85 _Ω DIF Zout | 11 = Reserved | |

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

SMBus Table: Pull-up Pull-down Control

| Byte 14 | Name | Control Function | Type | 0 | 1 | Default |
|---------|--------------|--|------|---------|---------------|---------|
| Bit 7 | OE1_pu/pd[1] | OE3 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 6 | OE1_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | Reserved | | | | | 1 |
| Bit 3 | OE0_pu/pd[1] | OE1 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 2 | OE0_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |
| Bit 1 | Reserved | | | | | 0 |
| Bit 0 | Reserved | | | | | 1 |

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

SMBus Table: Pull-up Pull-down Control

| Byte 15 | Name | Control Function | Type | 0 | 1 | Default |
|---------|--------------|--|------|---------|---------------|---------|
| Bit 7 | Reserved | | | | | 0 |
| Bit 6 | Reserved | | | | | 1 |
| Bit 5 | OE3_pu/pd[1] | OE6 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 4 | OE3_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |
| Bit 3 | Reserved | | | | | 0 |
| Bit 2 | Reserved | | | | | 1 |
| Bit 1 | OE2_pu/pd[1] | OE4 Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 0 |
| Bit 0 | OE2_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |

SMBus Table: Pull-up Pull-down Control

| Byte 16 | Name | Control Function | Type | 0 | 1 | Default |
|---------|------------------------|--|------|---------|---------------|---------|
| Bit 7 | Reserved | | | | | X |
| Bit 6 | Reserved | | | | | X |
| Bit 5 | Reserved | | | | | X |
| Bit 4 | Reserved | | | | | X |
| Bit 3 | HIBW_BYPM_LOBWpu/pd[1] | HIBW_BYPM_LOBW Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 1 |
| Bit 2 | HIBW_BYPM_LOBWpu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 1 |
| Bit 1 | CKPWRGD_PD_pu/pd[1] | CKPWRGD_PD Pull-up(PuP)/ Pull-down(Pdwn) control | RW | 00=None | 10=Pup | 1 |
| Bit 0 | CKPWRGD_PD_pu/pd[0] | | RW | 01=Pdwn | 11 = Pup+Pdwn | 0 |

Note: xx42 = 10, xx52 = 01, P2 = factory programmable.

Bytes 17 is Reserved

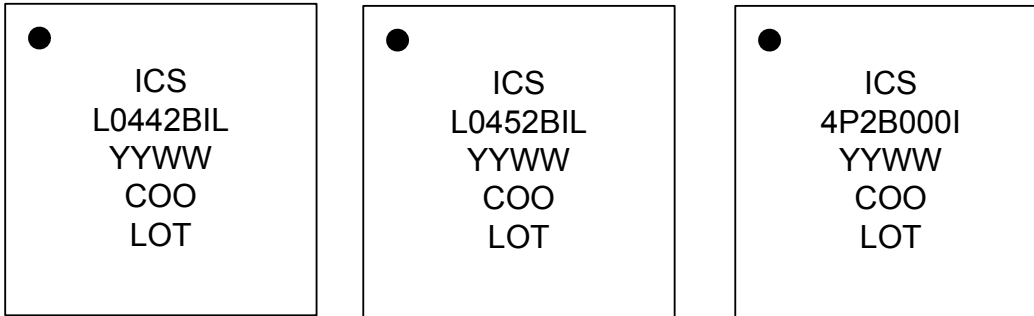
SMBus Table: Polarity Control

| Byte 18 | Name | Control Function | Type | 0 | 1 | Default |
|---------|--------------|-------------------|------|------------------|-------------------|---------|
| Bit 7 | Reserved | | | | | 0 |
| Bit 6 | OE3_polarity | Sets OE6 polarity | RW | Enabled when Low | Enabled when High | 0 |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | OE2_polarity | Sets OE4 polarity | RW | Enabled when Low | Enabled when High | 0 |
| Bit 3 | OE1_polarity | Sets OE3 polarity | RW | Enabled when Low | Enabled when High | 0 |
| Bit 2 | Reserved | | | | | 0 |
| Bit 1 | OE0_polarity | Sets OE1 polarity | RW | Enabled when Low | Enabled when High | 0 |
| Bit 0 | Reserved | | | | | 0 |

SMBus Table: Polarity Control

| Byte 19 | Name | Control Function | Type | 0 | 1 | Default |
|---------|------------|-----------------------------------|------|------------------------|-------------------------|---------|
| Bit 7 | Reserved | | | | | 0 |
| Bit 6 | Reserved | | | | | 0 |
| Bit 5 | Reserved | | | | | 0 |
| Bit 4 | Reserved | | | | | 0 |
| Bit 3 | Reserved | | | | | 0 |
| Bit 2 | Reserved | | | | | 0 |
| Bit 1 | Reserved | | | | | 0 |
| Bit 0 | CKPWRGD_PD | Determines CKPWRGD_PD polarity | RW | Power Down when Low | Power Down when High | 0 |

Marking Diagrams



Notes:

1. "LOT" is the lot sequence number.
2. "COO" denotes country of origin.
3. "YYWW" is the last two digits of the year and week that the part was assembled.
4. Line 2: truncated part number
5. "I" denotes industrial temperature range device.

Thermal Characteristics

| PARAMETER | SYMBOL | CONDITIONS | PKG | TYP VALUE | UNITS | NOTES |
|--------------------|----------------|---------------------------------|-------|-----------|-------|-------|
| Thermal Resistance | θ_{JC} | Junction to Case | NLG32 | 42 | °C/W | 1 |
| | θ_{Jb} | Junction to Base | | 2.4 | °C/W | 1 |
| | θ_{JA0} | Junction to Air, still air | | 39 | °C/W | 1 |
| | θ_{JA1} | Junction to Air, 1 m/s air flow | | 33 | °C/W | 1 |
| | θ_{JA3} | Junction to Air, 3 m/s air flow | | 28 | °C/W | 1 |
| | θ_{JA5} | Junction to Air, 5 m/s air flow | | 27 | °C/W | 1 |

¹ePad soldered to board

Package Outline and Dimensions (NLG32)

| REVISIONS | | | |
|-----------|-------------------------|--------|----------|
| REV | DESCRIPTION | DATE | APPROVED |
| 00 | INITIAL RELEASE | 2/1/16 | JH |
| 01 | ADD "k," VALUE MIN 0.20 | 2/8/16 | JH |

| SYMBOL | DIMENSION | |
|--------|-----------|----------|
| | MIN | MAX |
| b | 0.18 | 0.30 |
| D | 5.00 BSC | |
| E | 5.00 BSC | |
| D2 | 3.00 | 3.30 |
| E2 | 3.00 | 3.30 |
| L | 0.30 | 0.50 |
| e | 0.50 BSC | |
| N | 32 | |
| A | 0.80 | 1.00 |
| A1 | 0.00 | 0.02 |
| A3 | 0.2 REF | |
| k | 0.20 | 0.53 REF |

TOP VIEW

SIDE VIEW

BOTTOM VIEW

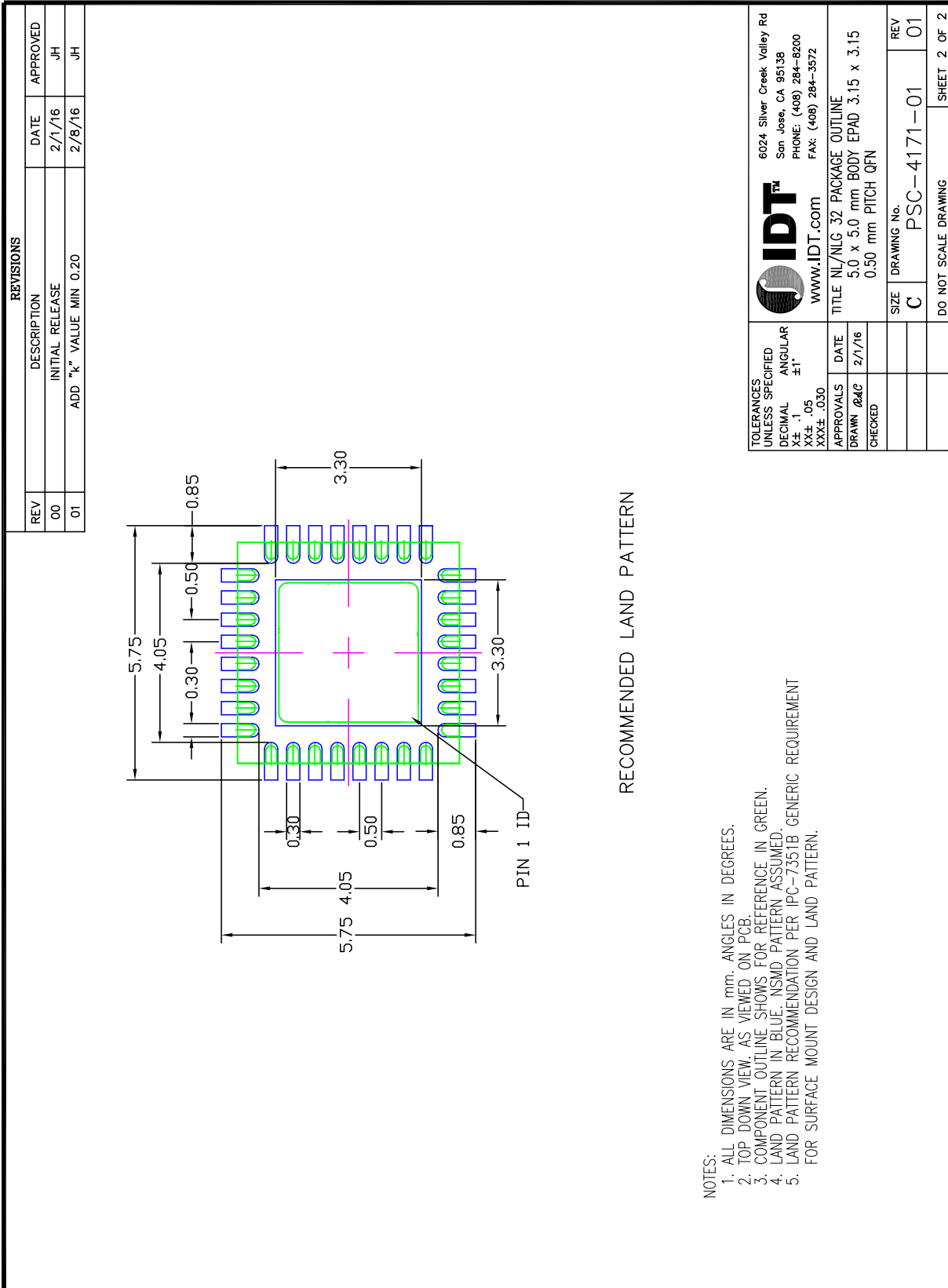
PIN #1 ID OPTION

NOTES:

- ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
- WARPAGE SHALL NOT EXCEED 0.08 mm.
- WARPAGE SHALL NOT EXCEED 0.10 mm.

| | | |
|---|---|--|
| <p>TOLERANCES UNLESS SPECIFIED</p> <p>DECIMAL ±1</p> <p>XX ±.05</p> <p>XXX ±.050</p> | <p>6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572 www.IDT.com</p> | <p>TITLE NL/NLG 32 PACKAGE OUTLINE</p> <p>5.0 x 5.0 mm BODY EPAD 3.15 x 3.15</p> <p>0.50 mm PITCH QFN</p> |
| <p>APPROVALS</p> <p>DATE 2/1/16</p> <p>DRAWN @JAC</p> <p>CHECKED</p> | <p>DRAWING No.</p> <p>C PSC-4171-01</p> | <p>REV</p> <p>01</p> |
| DO NOT SCALE DRAWING | | |
| | | SHEET 1 OF 2 |

Package Outline and Dimensions (NLG32), cont.



Ordering Information

| Part / Order Number | Notes | Shipping Packaging | Package | Temperature |
|---------------------|---|--------------------|---------------|---------------|
| 9DBL0442BKILF | 100Ω | Trays | 32-pin VFQFPN | -40 to +85° C |
| 9DBL0442BKILFT | | Tape and Reel | 32-pin VFQFPN | -40 to +85° C |
| 9DBL0452BKILF | 85Ω | Trays | 32-pin VFQFPN | -40 to +85° C |
| 9DBL0452BKILFT | | Tape and Reel | 32-pin VFQFPN | -40 to +85° C |
| 9DBL04P2BxxxKILF | Factory configurable. Contact IDT for additional information. | Trays | 32-pin VFQFPN | -40 to +85° C |
| 9DBL04P2BxxxKILFT | | Tape and Reel | 32-pin VFQFPN | -40 to +85° C |

“LF” suffix to the part number are the Pb-Free configuration and are RoHS compliant.

“B” is the device revision designator (will not correlate with the datasheet revision).

“xxx” is a unique factory assigned number to identify a particular default configuration.

Revision History

| Rev. | Initiator | Issue Date | Description | Page # |
|------|-----------|------------|---|---------|
| A | RDW | 5/31/2016 | <ol style="list-style-type: none"> 1. Add PCIe G1-4 Common Clock and PCIe SRIS to electrical tables 2. Update Electrical Tables to final 3. Changed '1' value in Byte 0 to indicate "Pin Control" 4. Stylistic update to block diagram 5. Minor updates to SMBus registers 0 and 1 for Readability 6. Front page text update for family consistency. 7. Removed '000' code from ordering information, updated table. 8. Minor corrections to Byte 1 [1:0] and Byte 11 [1:0] | Various |
| B | RDW | 6/14/2016 | <ol style="list-style-type: none"> 1. Electrical Table and SMBus Updates/Corrections 2. Release to final. | Various |
| C | RDW | 6/21/2016 | <ol style="list-style-type: none"> 1. Updated ESD from 2000V to 2500V | 5 |
| D | RDW | 11/11/2016 | <ol style="list-style-type: none"> 1. Corrected pin 32 to indicate an internal pull down resistor, not a pull up resistor. | 2, 3 |
| E | RDW | 2/8/2017 | Renamed datasheet to 9DBL0442 / 9DBL0452 | Various |
| F | RDW | 2/22/2017 | Replaced POD drawing from P3 [3.10 EPAD] to P1 [3.15 EPAD] option. | 16, 17 |



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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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